METHOD FOR BONDING TWO SUBSTRATES

Abstract

The invention relates to a method for bonding two substrates, comprising the steps of applying an activation treatment to at least one of the substrates, and performing the contacting step of the two substrates under partial vacuum. Due to the combination of the two steps, it is possible to carry out the bonding and obtain high bonding energy with a reduced number of bonding voids. The invention is in particular applicable to a substrate comprising processed or at least partially processed devices.

FIG. 1e